

**In the Claims:**

Claims 1-27 (canceled).

**Claim 28 (currently amended):** A method comprising steps of:

covering a first area ~~in~~of a dielectric layer, said dielectric layer having a first dielectric constant;

exposing a second area in said dielectric layer to a dielectric conversion source so as to increase said first dielectric constant of said dielectric layer in said second area to a second dielectric constant;

etching a plurality of capacitor trenches in said second area in said dielectric layer;

wherein said dielectric conversion source ~~comprises~~is selected from the group consisting of E-beams, I-beams, an amine based chemical, and an oxygen plasma.

**Claim 29 (currently amended):** A method comprising steps of:

etching a plurality of capacitor trenches in a second area in a dielectric layer, said dielectric layer having a first dielectric constant;

covering a first area ~~in~~of said a dielectric layer, ~~said dielectric having a first dielectric constant;~~

Attorney Docket No.: 99CON114P

exposing asaid second area in said dielectric layer to a dielectric conversion source so as to increase said first dielectric constant of said dielectric layer in said second area to a second dielectric constant;

wherein said dielectric conversion source ~~comprises~~ is selected from the group consisting of I-beams, E-beams, an amine based chemical, and an oxygen plasma.

**Claim 30 (currently amended):** A method comprising steps of:

covering a first area in a dielectric, said dielectric having a first dielectric constant;  
exposing a second area in said dielectric to a dielectric conversion source so as to increase said first dielectric constant of said dielectric in said second area to a second dielectric constant, wherein said covering said first area in said dielectric prevents said first area from being exposed to said dielectric conversion source;

wherein said dielectric conversion source comprises an amine based chemical.

**Claim 31 (currently amended):** A method comprising steps of:

covering a first area in a dielectric, said dielectric having a first dielectric constant;  
exposing a second area in said dielectric to a dielectric conversion source so as to increase said first dielectric constant of said dielectric in said second area

Attorney Docket No.: 99CON114P

to a second dielectric constant, wherein said covering said first area in said dielectric prevents said first area from being exposed to said dielectric conversion source;

wherein said dielectric conversion source comprises oxygen plasma.